## LN1251CALTR

### Hight Bright Surface Mounting Chip LED

J Type

#### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Power dissipation	$P_{\mathrm{D}}$	45	mW	
Forward current	$I_{\mathrm{F}}$	15	mA	
Pulse forward current *	$I_{FP}$	60	mA	
Reverse voltage	V <sub>R</sub>	3	V	
Operating ambient temperature	T <sub>opr</sub>	-25 to +80	°C	
Storage temperature	T <sub>stg</sub>	-30 to +85	°C	

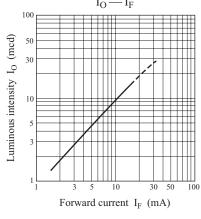
Note) \*: The condition of  $I_{\text{FP}}$  is duty 10%, Pulse width 1 msec.

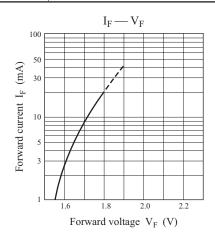
#### ■ Lighting Color

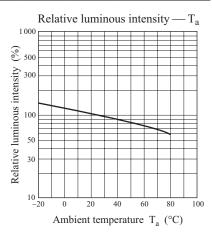
• Red

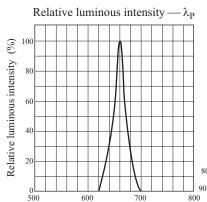
#### ■ Electro-Optical Characteristics $T_a = 25$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I <sub>O</sub>	$I_F = 10 \text{ mA}$	3.3	9.0		mcd
Reverse current	$I_R$	$V_R = 3 V$			100	μΑ
Forward voltage	V <sub>F</sub>	$I_F = 15 \text{ mA}$		1.75	2.6	V
Peak emission wavelength	$\lambda_{\mathrm{P}}$	$I_F = 15 \text{ mA}$		660		nm
Spectral half band width	Δλ	$I_F = 15 \text{ mA}$		20		nm

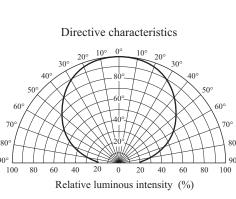


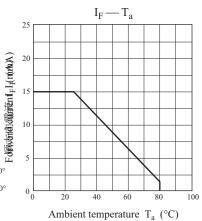






Peak emission wavelength  $\lambda_P$  (nm)

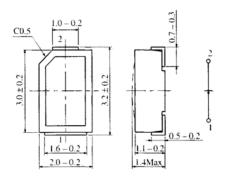




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■ Package (Unit: mm)

## LLDFTR2G5110



- Pin name
  - 1: Anode
  - 2: Cathode

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